

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.		MDG/20/12191
1.3 Title of PCN		ASE Kaohsiung (Taiwan) additional source and Product enhancement for STM32MP15x in LFBGA18X18 package source
1.4 Product Category		LFBGA18X18 for STM32MP15x products
1.5 Issue date		2020-06-16

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Ricardo Antonio DE SA EARP
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Crolles 300 (France) AMKOR ATK (Korea) ASE KaoHsiung (Taiwan)

4. Description of change

	Old	New
4.1 Description	Product revision B (cut 2.0) Limitations as described in Errata Sheet ES0438 Revision 3 - November 2019 "STM32MP151x STM32MP153x STM32MP157x" Summary of Device errata Package source: - Amkor ATK (Korea)	New Product Revision Z (cut 2.1) - New Errata sheet ES0438 Revision 4 - January 2020 "STM32MP151x STM32MP153x STM32MP157x" Summary of Device errata Package dynamic warpage improvement - Amkor ATK (Korea) - existing source - ASE Kaohsiung (Taiwan) - Additional source
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Function enhancement (New die revision from B to Z) Additional Assembly site	

5. Reason / motivation for change

5.1 Motivation	New Die revision: product enhancement New Assembly Site: Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Please refer to PCN12191 Additional information attached document.
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7. Timing / schedule

7.1 Date of qualification results	2020-09-21
7.2 Intended start of delivery	2020-10-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	12191 MDG-MCD-RERMCD2008 -RERMCD2010 -PCN12191-reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2020-06-16

9. Attachments (additional documentations)

12191 Public product.pdf
12191 MDG-MCD-RERMCD2008 -RERMCD2010 -PCN12191-reliability plan.pdf
12191 PCN12191_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32MP151AAA3	
	STM32MP151CAA3	
	STM32MP153AAA3	
	STM32MP153CAA3	
	STM32MP157AAA3	
	STM32MP157CAA3	

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